



THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application

Title: PROCESS FOR FORMING A DIRECT BUILD-UP LAYER ON AN
ENCAPSULATED DIE PACKAGES UTILIZING INTERMEDIATE STRUCTURES

Docket No.: 884.791US1
Filed: September 14, 2000
Examiner: Unknown
Customer No.: 21186

Serial No.: 09/661,899
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Confirmation No.:

Commissioner for Patents
Attn: MAIL STOP ISSUE FEE
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